



Click [here](#) for the 3D model.

Dimensions

Footprint	7238
L	7.24mm +/-0.38mm
W	3.81mm +/-0.38mm
H	2.79mm +/-0.38mm
S	1.27mm +0.25/-0.13mm
F	3.68mm +0.13/-0.51mm
K	1.52mm MIN
P	0.76mm MIN

Packaging Specifications

Packaging	T&R, 178mm
Packaging Quantity	500

General Information

Series	T409 CWR09
Dielectric	MnO2 Tantalum
Style	SMD Chip
Description	SMD, MnO2, Molded, Military Equivalent
RoHS	No
Prop 65	⚠ WARNING: Cancer and reproductive harm - http://www.p65warnings.ca.gov .
SCIP Number	652b281f-d242-4453-bc44-0655d646cec3
Termination	Hot Solder Dipped
Qualifications	MIL-PRF-55365/4, CWR09 Style
AEC-Q200	No
Component Weight	349.01 mg
Notes	Note: When Option C Is Selected For Lead Material, Add An Additional 0.38mm To The Tolerances For "L", "W", "H", "K", "F" And "S".
MSL	1

Specifications

Capacitance	4.7 uF
Capacitance Tolerance	10%
Voltage DC	50 VDC (85C), 33.5 VDC (125C)
Temperature Range	-55/+125°C
Rated Temperature	85°C
Dissipation Factor	6% 120Hz 25C
Failure Rate	B (0.1%/1000 Hrs)
Resistance	1.5 Ohms (100kHz 25C)
Ripple Current	316 mA (rms, 100kHz 25C)
Leakage Current	3 uA (5min 25°C)
Testing and Reliability	Surge Testing (10 Cycles At 25C After Weibull)